

EU Funding: Industry4.0 Focus and Challenges of the ECSEL Joint Undertaking

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ELECTRONICS HAS PROFOUNDLY CHANGED OUR SOCIETY







1. What is ECSEL?

- 1. Governance
- 2. Calls
- 3. ECS Community
- 2. ECSEL and Industry 4.0
- 3. ECSEL and the Czech participation
- 4. What will come next?

Electronic
Components and
Systems for
European
Leadership



ECSEL: A Unique Model to Promote European Innovation

TRIPARTITE=3 – Partnering
JU = Joint Undertaking

European Commission

Promote synergies between commercial strategies and societal needs

64 projects
2161 beneficiaries
3 385 million Euro cost
1 174 million Euros in funding

2014-2018

Re-inforce/Align
National strategies
and European
priorities

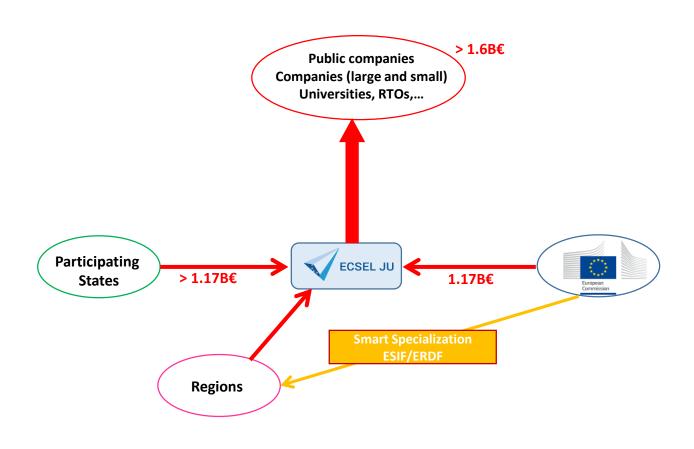
3 (Industry) Associations: AENEAS EPOSS ARTEMISIA

28 ECSEL Participating
States



JU: COMMON GOVERNANCE + COMMON FUNDING

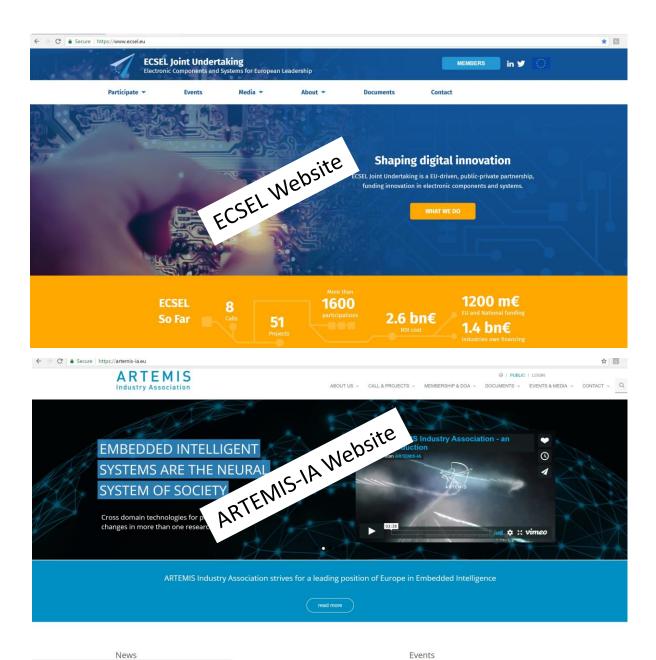




Contributions EU:EPS:Benefiaries in 1:1:2 proportion

ECSEL Participating States: EU Member States and Israel, Norway, Switzerland and Turkey Also participating: US, Canada, Taiwan, Brasil



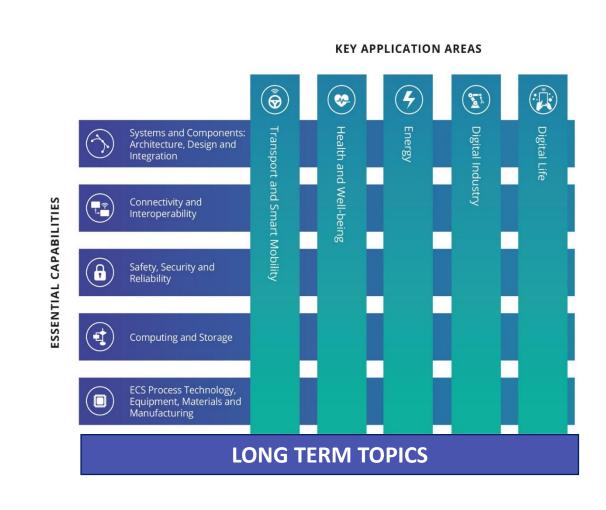




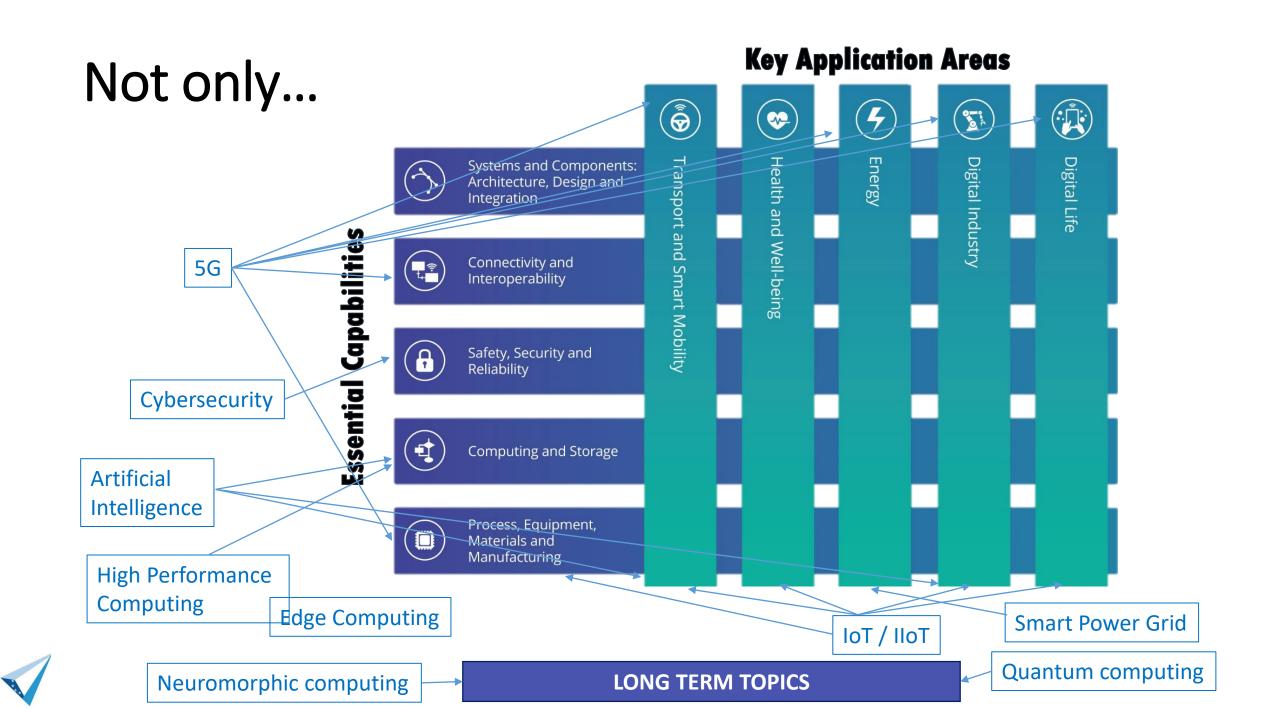


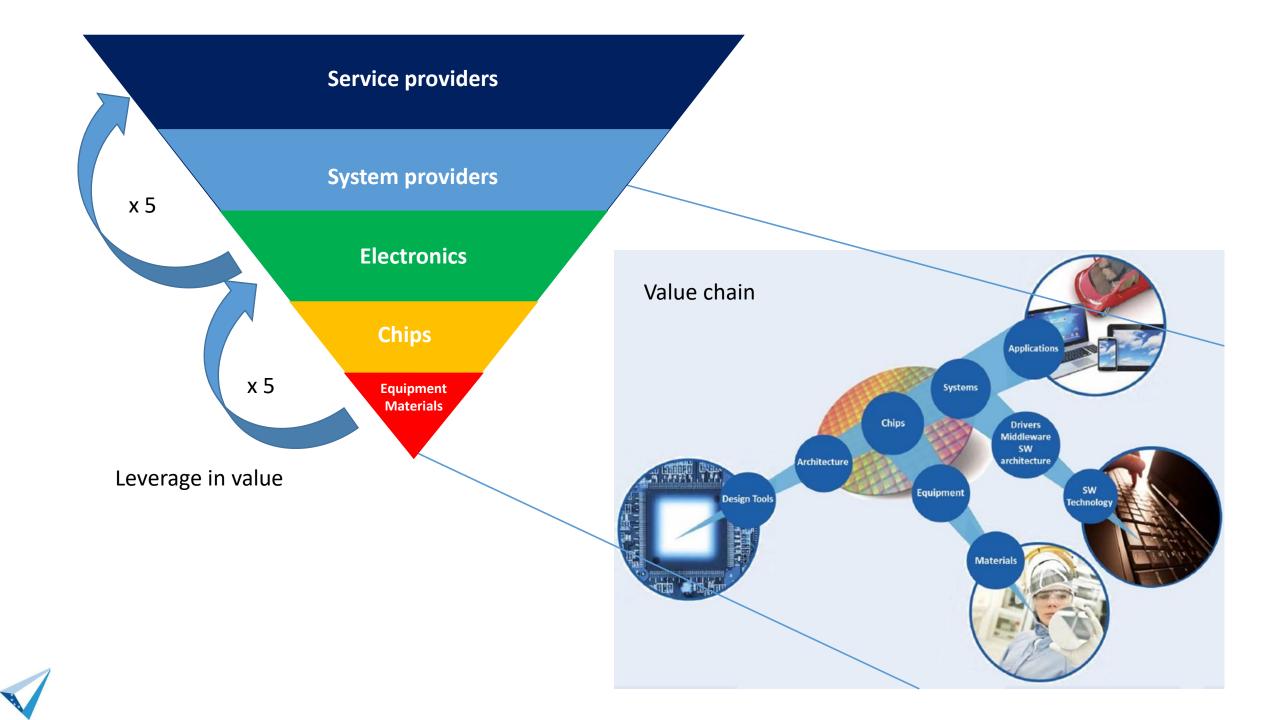
A common strategy: Strategic Research Agenda (SRA)

- 3 Industry Associations (not only also SMEs, Universities, RTOs)
 - AENEAS
 - ARTEMIS-IA
 - EPoSS
- SRA is adopted by the Governing Board: SRA becomes MASP
- A revision of the SRA to prepare KDT is foreseen

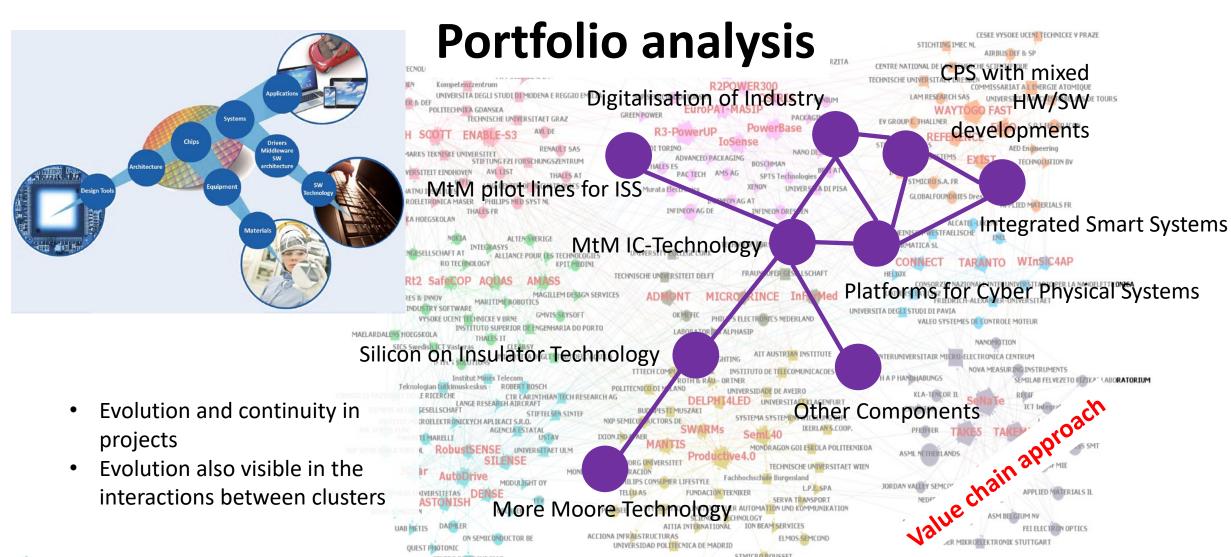








ECSEL: Networks of Partners and Projects

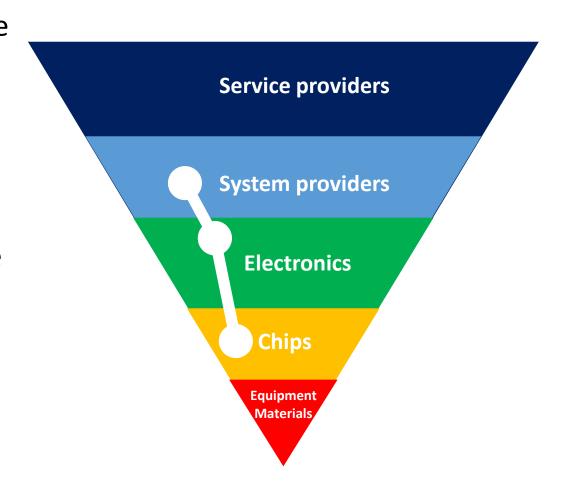




ECSEL cooperating with other programmes

ECSEL projects reach out to programmes outside of ECSEL: **value chain** stakeholders, other associations or programmes, etc by:

- Developing standards
- Using roadmaps and priorities of other organisations
- Integrating communities outside ECSEL in the ECSEL value chains
- Developing key enabling technologies enabling technologies of other programmes/ sectors





3Ccar	DENSE	WInSiC4AP	HiPERFORM
EXIST	PRIME	EuroPAT-MASIP	PRYSTINE
MANTIS	REFERENCE	MICROPRINCE	SECREDAS
OSIRIS	SafeCOP	Productive4.0	AI4DI
RobustSENSE	ENABLE-S3	R3-PowerUP	Applause
SWARMs	EnSO	SCOTT	Arrowhead Tools
ADMONT	IoSense	TAKEMI5	Comp4Drones
InForMed	SemI40	iDev40	CPS4EU
PowerBase	TAKES	QCEAN12	Heliaus
R2POWER300	DATUAS 14-	2012 POSITION-II	MadeIn4
SeNaTe 0	TAKES AUTODIVE CONNECT	REACTION	NewControl
WAYTOODAG	CONNECT	TAPES3	Pin3S
3DAM	I-MECH	WAKeMeUP	PowerToPower
AMASS	MegaMaRt2	5G_GaN2	TEMPO
ASTONISH	SILENSE	AFarCloud	UltimateGaN
DELPHI4LED	TARANTO	FITOPTIVIS	ViZta



ECSEL Calls for proposals

EVERY YEAR:

Example:

Calls 2019

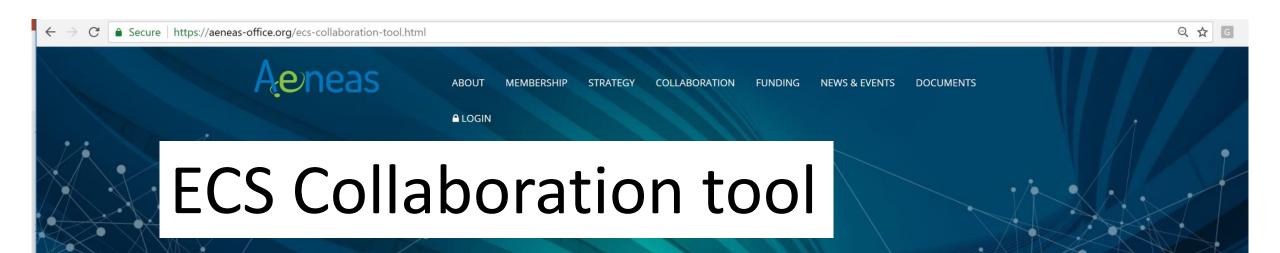
1x RIA and 1x IA calls (all topics open)

+ Special topics, special call

In 2020: common call with IMI JU

PO **FPP EVALUAT EVALUATIONS IONS** feb jun dec jul oct nov mar apr may aug sep Calls opened PO **FPP Funding** 6/2/2019 decision **Deadline Deadline** 7/5/2019 1/9/2019 **ECSEL Calls Webinar** Inform **Inform** 13/2/2019 **Applicants Applicants**

How to participate?





ARTEMIS-IA and AENEAS have now merged their collaboration support tools into a single co-managed service: the ECS Collaboration Tool. AENEAS and ARTEMIS Industry Association wanted to create one tool to facilitate easy information exchange within the ECS community and allow the collection and management of all relevant data, ideas and project proposals in one place.

Join an efficient community tool

The ECS Collaboration Tool is open to all in the ECS Community, and available 24/7. The new tool is released to prepare for joint consortium building at EFECS, but is available to support any related event, regardless of the funding instrument involved. It can

Join ECS tool

Getting involved



Create a project idea

Initiate a project idea in the ECS Collaboration tool, invite partners and browse other project ideas.



Look for a partner

Use the partner search on ECS Collaboration Tool to look for possible partners based on their expertise and invite them to join your project idea.



Look for other project ideas

Browse through the ECS Collaboration Tool to find project ideas and send out a online request to join

Attend the Events

- Conferences: EFECS
- Workshops
- Brokerage events
- ECSEL Symposium
- etc



Events



Upcoming events







- 1. What is ECSEL?
- 2. ECSEL and Industry 4.0

11 out of 64 projects work on Industry4.0

- 1. Examples of projects
- 2. Lighthouse initiative: Industry 4.E
- 3. ECSEL and the Czech participation
- 4. What will come next?

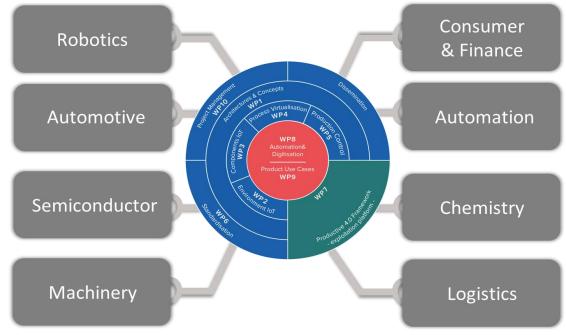


PRODUCTIVE 4.0 (2016, 115 partners, 105MEuro cost)



Significant improvement in digitalizing the European industry by means of electronics and ICT.

- aiming at suitability for everyday application
- various industrial domains with same approach of digitalization.



ELECTRONICS AND ICT AS ENABLER FOR DIGITAL INDUSTRY AND OPTIMIZED SUPPLY CHAIN MANAGEMENT COVERING THE ENTIRE PRODUCT LIFECYCLE



Key partners: BMW, Philips, Infineon, ABB, NXP, STM, BOSCH, Thales, AVL, VOLVO, CEA, BetterSolutions, IMA, KIT, AIT, FhG, Sysgo, DANOBAT, MONDRAGON, ERICSSON, VTT, SINTEF, LTU, LFOUNDRY, TNO, TTTech, Siltronic, VIF and many more..

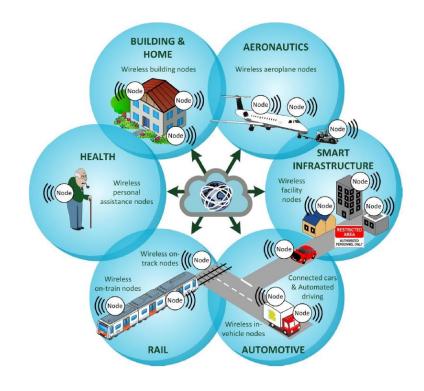


SCOTT (2016, 57 partners, 39MEuro cost)

Secure COnnected Trustable Things

One of the objectives: Evaluate compatibility and interoperability with other reference standards and architectures, validating the global applicability of SCOTT reference architecture (HLA). (incl.5G)







LIGHTHOUSE INITIATIVES

MOBILITY.E
INDUSTRY4.E
HEALTH.E

A container of coordinated activities coming from different programmes using their synergy to achieve overarching common goals.





Industry4.E

LIASE

- Andrew Lynch (IMR)
- (Chris Decubbere)
- Eduardo Beltran (Mondragon Corporation)
- Knut Hufeld (Infineon DE)
- Olli Ventä (VTT)

Support

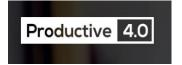
- ECSEL Office
- DG Connect
- CSA_Industry4.E





















Public Private Partnership

Industry4.E: R&D&I + cross-cutting aspects

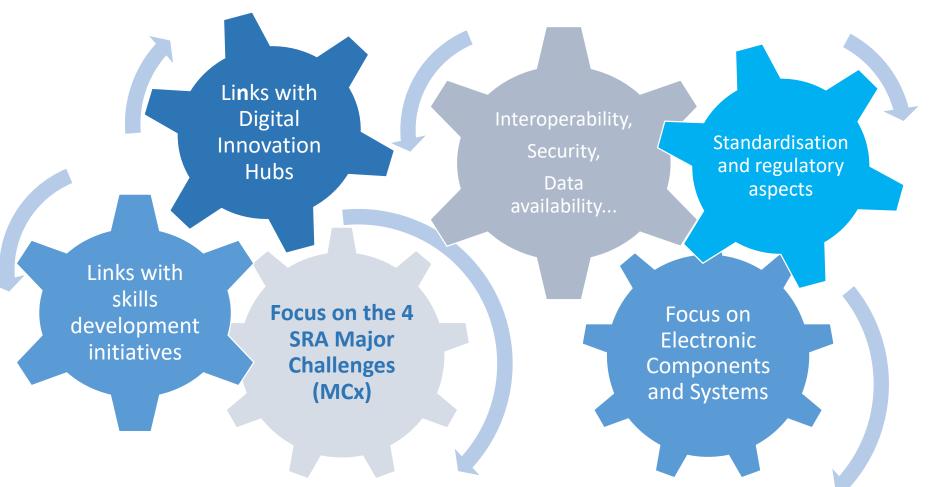
MC1: Developing Digital twins, simulation models...

MC2: Implementing AI and machine learning...

MC3: Generalizing

conditions monitoring...

MC4: Developing digital platforms, application development frameworks that integrate sensors and systems



Evaluate overlap/complementarity with other running or future programmes/activities

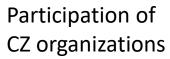
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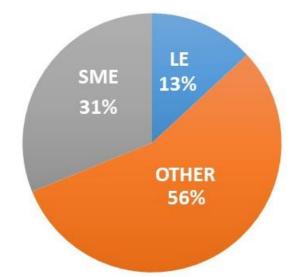


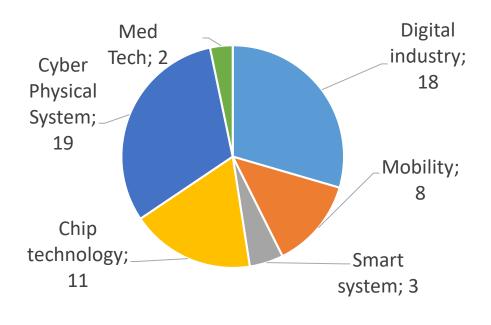
Czech participation to ECSEL JU

- Projects: 23 (CZ participation in 37% of the selected ECSEL projects!) (I'll discuss the 8 most recent)
- Partners: 6 Large companies, 8 universities, 7 SMEs
- Funding: EU funding: 8.3M€, National funding: 11.1M€,
 Total cost: 26.7M€
- ENIAC ARTEMIS
- National rules

Participation of CZ organizations as a function of topic







NewControl (2018, 48 partners, 43MEuro cost)

<u>Title</u>: Integrated, Fail-Operational, Cognitive Perception, Planning and

Control Systems for Highly Automated Vehicles

<u>Topic</u>: Mobility

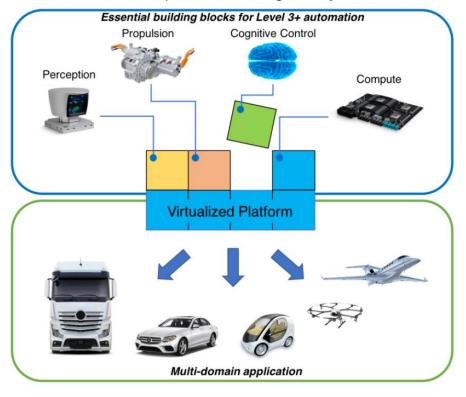
Czech participants:

- IMA (INSTITUT MIKROELEKTRONICKYCH APLIKACI S.R.O., SME): develop Car Access Control Unit involving mobile application, invehicle interfaces and secure communication layer to infrastructure. Fail-operational authentication algorithms for access control will be developed.
- BUT (Brno University of Technology): development of control and monitoring algorithms for highly efficient powertrain and LIDAR data processing. The contribution covers algorithms development and implementation on embedded controller hardware. The team will provide key expertise in advanced control and signal processing algorithms and their implementation in industry-used embedded systems with application in automotive technologies and robotics.



NEWCONTROL

Holistic virtualized platforms enabling mobility as a service



COMP4DRONES (2018, 53 partners, 27MEuro cost)

<u>Title</u>: Framework of key enabling technologies for safe and autonomous drones' applications

Topic: CPS Cooperation with SESAR JU

Czech participants:

- BUT
- **UWB (University of West Bohemia):** provide tools and methods for modelling simulation and control of drones at various levels and could add value to the project in modelling and simulation of various drone architectures, also dealing with redundant architectures.
- HON (Honeywell International): methods and tools for automated formal verification of requirements and system design of artificial intelligence-based system. The goal is to develop a use case Artificial Intelligence Based Adaptive Diagnostics of Electromotors and verify it using traditional verification techniques (mainly testing) as well as using proposed formal verification approach.
- SM (Smart-Motion, SME): Mechanical engineering, mechanical simulation, engineering support
- MU (Masaryk University): Evaluate applicability and benefits of formal verification tool for aerospace case study
 Artificial Intelligence Based Adaptive Diagnostics of Electromotors.

AI4DI (2018, 41 partners, 30MEuro cost)

Title: Artificial Intelligence for Digitalizing Industry

<u>Topic</u>: **Digital Industry** Al

Czech Participants:

- BUT: key contribution in AI algorithms for mechatronic systems fault detection and robot navigation
- IMA: providing IoT sensors, actuators and gateway within warehouse/production environment put on human and machines/objects. Human Machine interaction takes place. Artificial Intelligence code implemented at the edge of the devices enables device independency when interfaces to upper systems fail while HM services are retained.

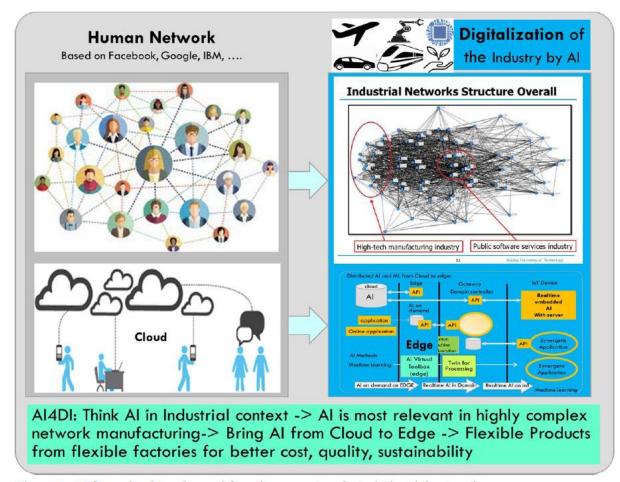


Figure 5: AI from cloud to edge and from human networks to industrial networks

Arrowhead Tools (2018, 90 partners, 90MEuro cost)

Manufacturers Know-how

Future Customer Requirements

<u>Title</u>: Arrowhead Tools for Engineering of Digitalisation Solutions

Topic: CPS **Digital Industry**

Czech Participants:

HON: methods and tools for automated formal verication of requirements and system design.

- UTIA (Institute of Information Theory and Automation, University): develop SW/HW board/project delivery tools for wide range of industrial computing nodes, board support packages for specific commercially supported design flow toolchain for the family of 16 nm UltraScale MP-SoC devices on multiple industrial grade carrier boards.
- MU (Masaryk University): development of algorithms, methods, and practical tools for program analysis and varication
- BUT: provide their experience with methods of ensuring software and hardware safety, including various kinds of automated static formal verification approaches as well as systematic testing and dynamic analysis capable of extrapolating results of testing and predicting possible failures even when they do not manifest during testing.
- CVUT (Czech Technical University in Prague): development tools for embedded real-time
 and safety-critical systems with a focus on automotive industry
- CAMEA, spol. s r.o.

SECREDAS (2017, 69 partners, 51MEuro cost)

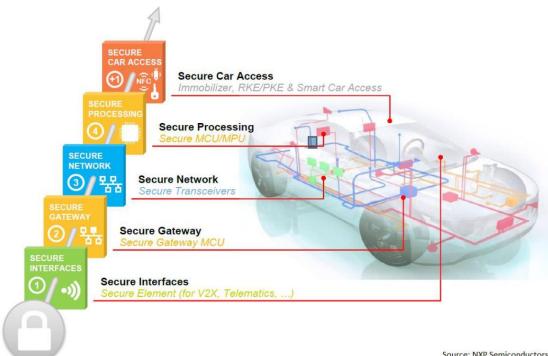
Title: Product **Security** for **Cross** Domain Reliable **D**ependable

Automated Systems

Topic: CPS Cybersecurity

Czech participants:

- **BUT**: contribute with authentication infrastructure to support evaluation of authentication supplicants and the primary contribution will be in development of robust secure supplicant code supporting RADIUS/DIAMETER protocols.
- IMA: create robust dynamic car access system based mixture of recent smart enablers. The innovative concept will be based on various identifiers, access right crosscheck, dynamic on line authentication and profiling by using BUT authentication server. Once the access check-in will be successfully accomplished, the authenticated identity of the driver will be liaison via standard SECREDAS Gateway to the in-vehicle system.



Source: NXP Semiconductors

FITOPTIVIS (2017, 31 partners, 22MEuro cost)

<u>Title</u>: From the cloud to the edge - smart IntegraTion and OPtimisation Technologies for highly efficient Image and VIdeo processing Systems <u>Topic</u>: CPS Imaging Czech participants:

- **CAM (CAMEA):** embedded video processing, specifically design and experimental research in embedded combination of FPGA and CPUs.
- **CUNI (UNIVERZITA KARLOVA):** specifying, modeling and developing components and models allowing for design-time and runtime adaptation in an edge-cloud enabled deployment.
- **REX (REX Controls s.r.o.):** Native support of the developed intelligent industrial camera sensor proposed by UWB in real-time control system
- BUT: embedded video processing, specifically object detection, recognition, and decsription.
- EDGE

 video

 smart sensors

 smart actuators

 smart devices

 user interaction

 CLOUD

 Servers, controlled by the CPS

 distributed computing

 $Figure \ 1 - FitOptiV is \ generic \ configuration \ of \ imaging \ and \ video \ pipelines \ in \ CPS$

- UWB (ZAPADOCESKA UNIVERZITA V PLZNI): Design and development of industrial camera sensor with integrated mathematical model of dynamics of the observed object
- UTIA (USTAV TEORIE INFORMACE A AUTOMATIZACE AV CR VVI): provide support mainly for Zynq Ultrascale+ 16 nm MPSOC design time resources and generic video processing IP cores and support for the board support packages enabling use of the commercial SDSoC design flow in the custom industrial system on modules with the 16nm MPSOC Zynq devices

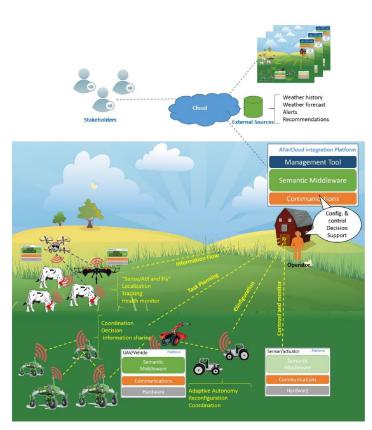
A Far Cloud (2017, 60 partners, 28MEuro cost)

Title: Aggregate FARming in the CLOUD

<u>Topic</u>: **Digital Industry** Agronomy

Czech participants:

- **IMA:** contribute in smart and secure identification, Identity management, system integration and sensors network implementation for IoT, provide basic data mining on gathered sensor data (correlation, profiling) for follow up applications.
- UWB: focus on specific aspect of livestock scenarios, namely development of additional sensory layer and data analysis SW modules for decision making layer
- IAS (VYZKUMNY USTAV ZIVOCISNE VYROBY V.V.I. UHRINEVES): contribute to sensor specifications, test of sensors provided by partner UWB for livestock health monitoring in dairy cows trial will contribute to overall architecture specification, namely from livestock point of view
- CUNI: modelling the agricultural system as a dynamic and evolving architecture of IoT and computational subsystems in an edge-cloud and smart coordination of such subsystems
- **LESP (LESPROJEKT SLUZBY SRO):** contribute to the analysis of use cases, design of architecture, implementation of tools formanagement of observation and also to the pilots in Czech and Latvia



WakeMeUp (2017, 18 partners, 96MEuro cost)

<u>Title</u>: Wafers for Automotive and other **Ke**y applications using **Me**mories, embedded in **U**lsi **P**rocessors

<u>Topic</u>: Chip Technology (SOI)

Czech participants:

- UTIA: develop SW stack and demos for low-power image processing WAKeMeUP SoC system with adaptation of the modified system level compiler toolchain
- IMA: involved in project tasks *T4.3 Embedded SW development* and *T5.2 Secure and General Purpose Application and System platform*.

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 - 1. Key Digital Technologies JU
 - 2. Digital Europe

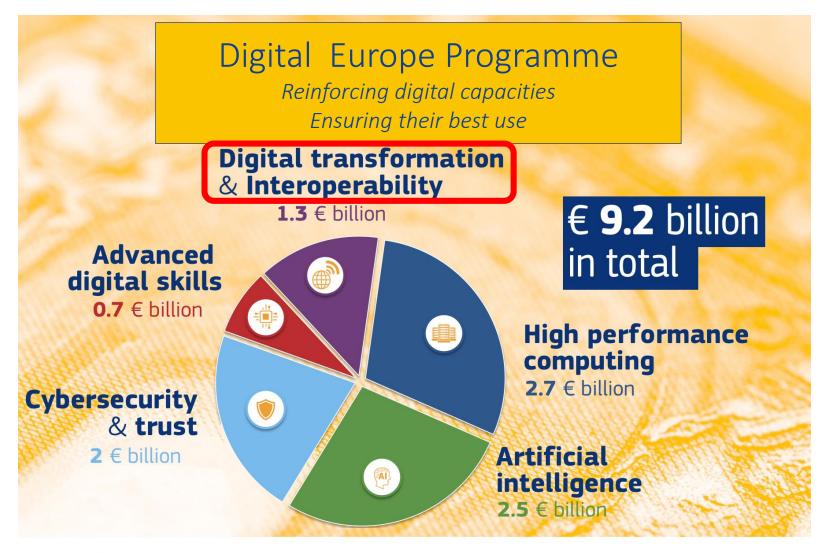


Horizon Europe: evolution not revolution





Digital Europe programme







END